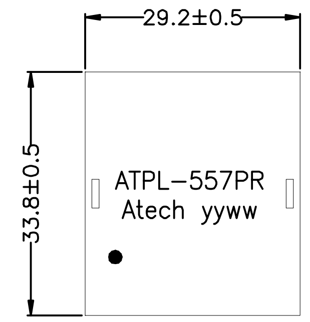
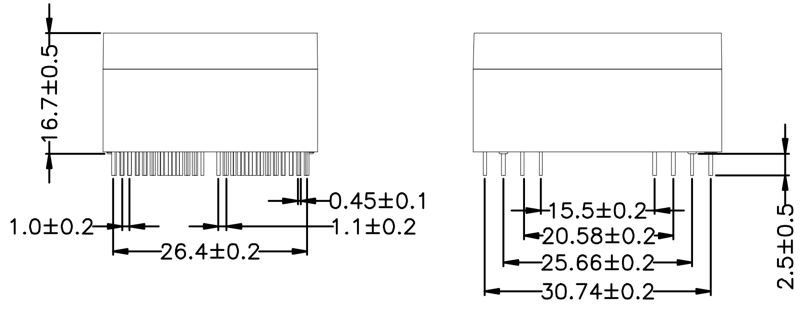
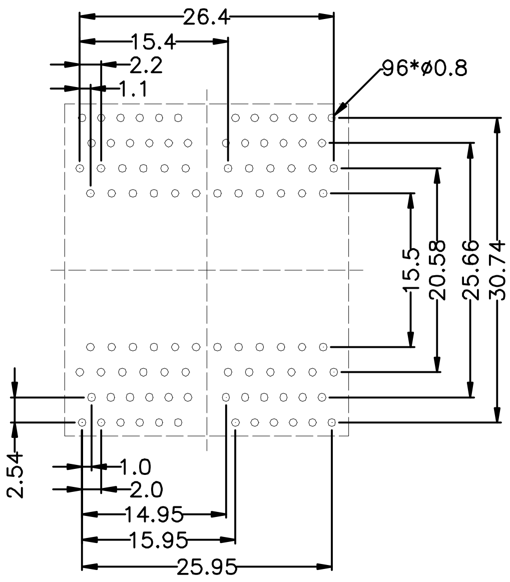
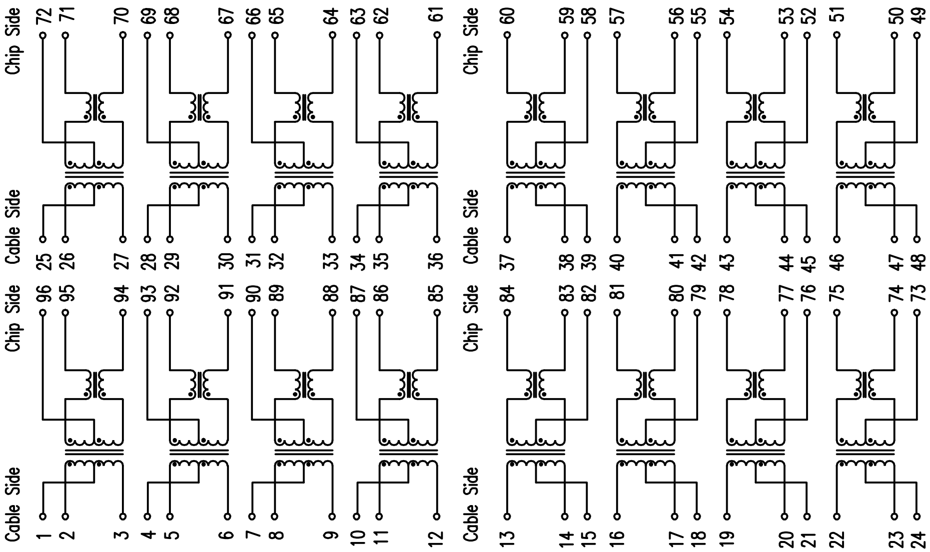






PCB Layout mounting Hole(Top View)



* RoHS COMPLIANT

ELECTRICAL CHARATERISTICS@25°C

1. OCL : (@100kHz, 0.1V With 14mA DC Bias) : 200uH MIN.
2. LEAKAGE INDUCTANCE : (@100kHz, 0.1V) : 0.5uH MAX.
3. DCR : 1.0Ω MAX.
4. TURNS RATIO : 1CT : 1CT ±5%
5. INSERTION LOSS : (@1–100MHz) : –1.0dB MAX.
   (@100–250MHz) : –2.0dB MAX.
6. RETURN LOSS : (@1≤f≤40MHz) : –16dB MIN.
   (@40≤f≤250MHz) : –16 + 10Log(f/40)dB MIN,
   where f is in MHz
7. CROSS TALK : (@1–250MHz) : –30dB MIN.
8. COMMON MODE REJECTION : (@1–250MHz) : –30dB MIN.
9. ISOLATION HIPOT : (@1500VAC, 1mA, 60S)
10. PoE Support 60W : Each channel support 720mA DC balance current
    Each channel support 1440mA DC balance current
11. OPERATING TEMPERATURE : 0°C TO +70°C
12. STORAGE TEMPERATURE : –40°C TO +85°C

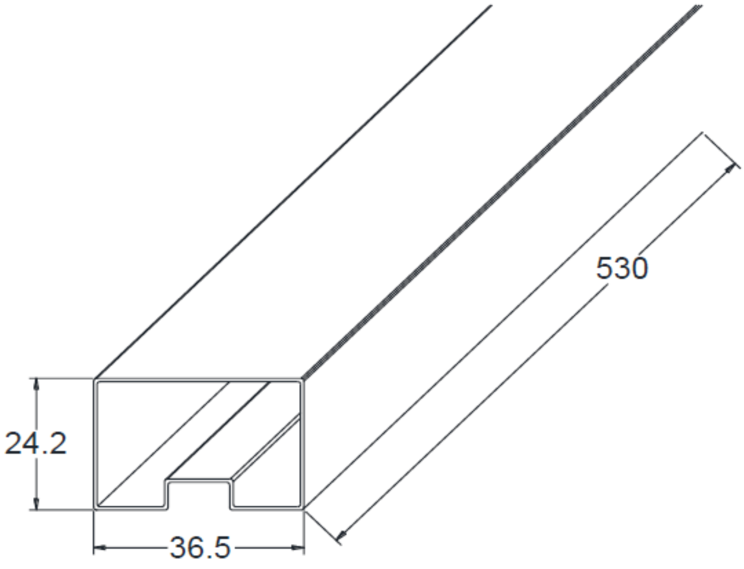
	RELEASE	02/25 /2022	SHIRLEY	BETTY	BETTY
NO:	DESCRIPTION	DATE	BY	CHK	APPD

REVISIONS

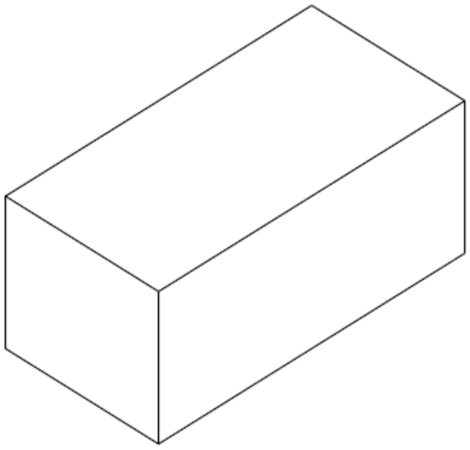
AOEM Atech

TITLE 2.5G/5G BASE-T TRANSFORMER
DWG. NO. ATPL-557PR
UNITS: M/M
SAFETY
SHEET 1 OF 1
DATE 02/25/22
P/N:
DRAW SHIRLEY

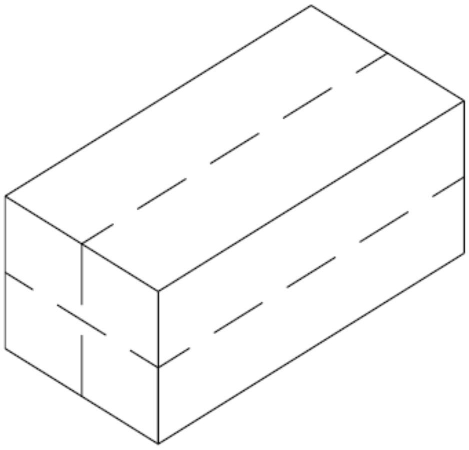
Package :



Tube：530*24.2*36.5mm



Inner Carton: L575*W170*H87mm



Export Carton: L583*W380*H210mm

Package Quantity:

One Tube=17Pcs

One Inner Carton=17*16=272Pcs

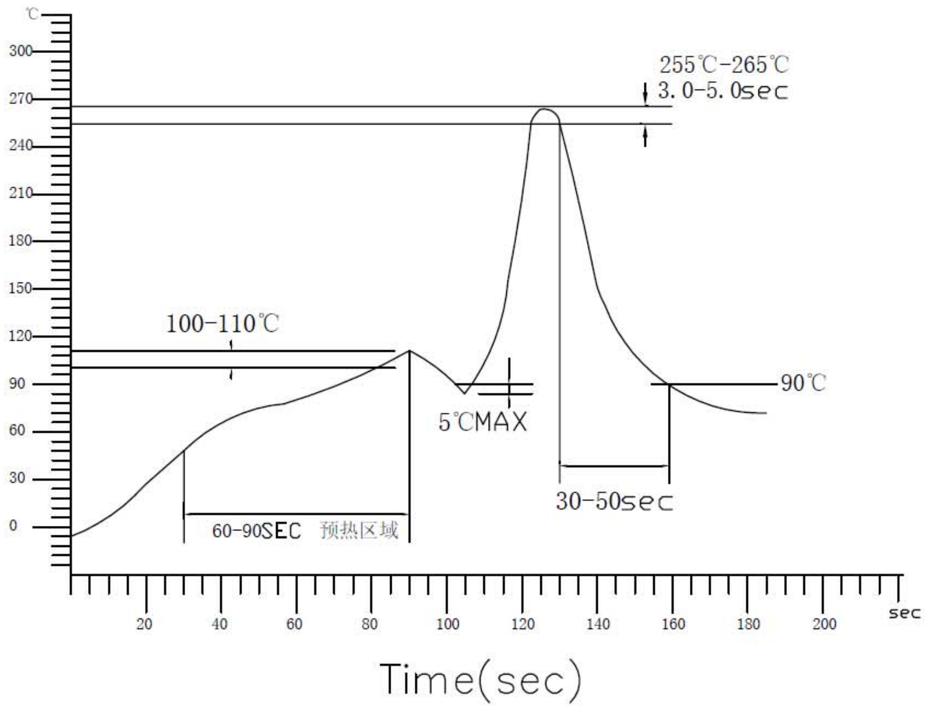
One Export Carton=272*4=1088Pcs

6. Soldering Heat Withstanding Survey (DIP)

Pb−free Soldering Heat Withstanding Survey(DIP)

Reflow conditions	Preheat area	Time at 220℃ or higher	Peak Temp	Holding time at 260℃ temp
Recommended conditi	Max 120s	Max 30s	260℃	Max 6S

Soldering Temp.profile



Soldering conditions	Soldering Temp.	Heating Time
Recommended conditions	260℃±5℃	Max 6 sec

Soldering Iron Conditions	Soldering Iron Temp	Heating Time
Recommended conditions	350±10℃	Max 5 sec

Part Electrode Plating Constitution	Sn.CU
Any other series applicable same conditions	NO
Packing Configuration	TRAY